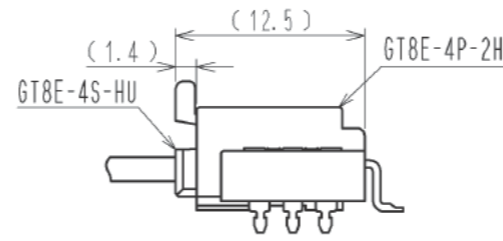
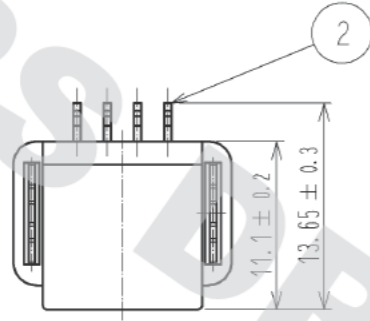
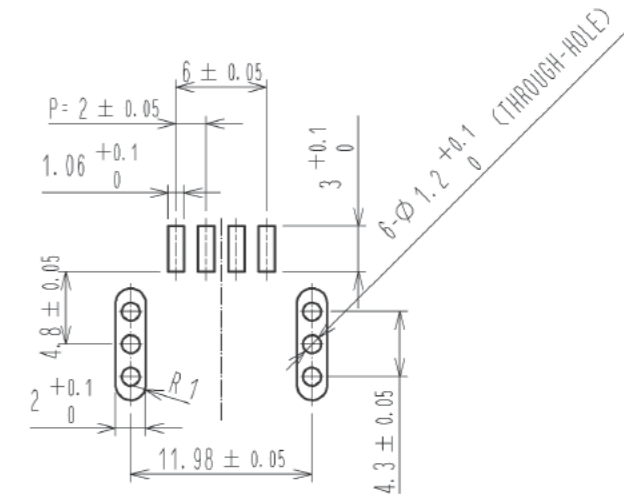


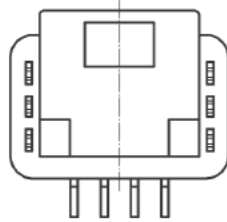
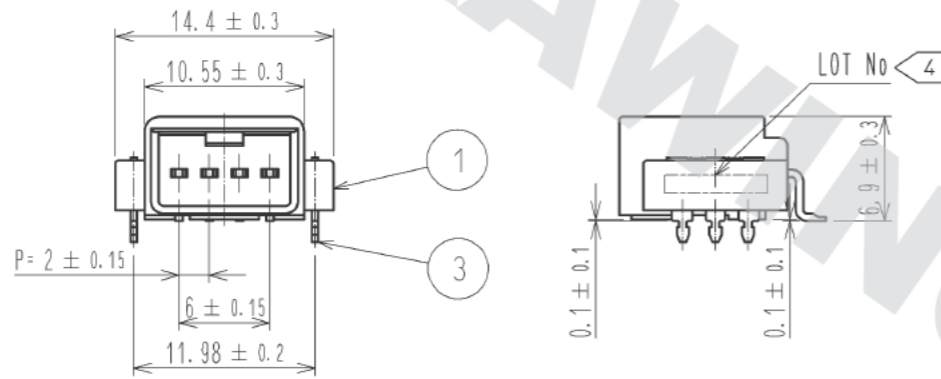
ELV. RoHS COMPLIANT



MATING CONFIGURATION



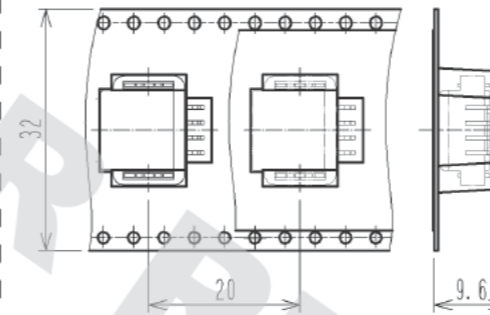
RECOMMENDED PC BOARD PATTERN



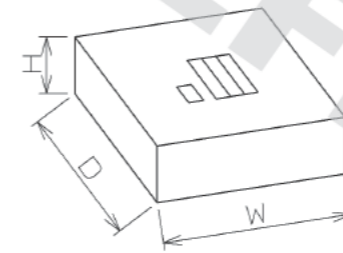
PACKING STYLE

1. Place connectors into an embossed carrier tape.

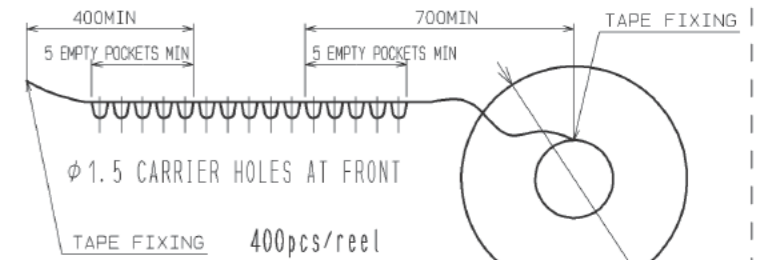
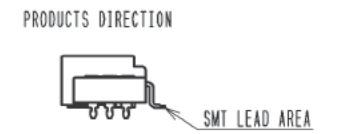
← DIRECTION OF UNREELING



2. Put a reel into a cardboard.



W = (405) (mm)
D = (405) (mm)
H = (39) (mm)



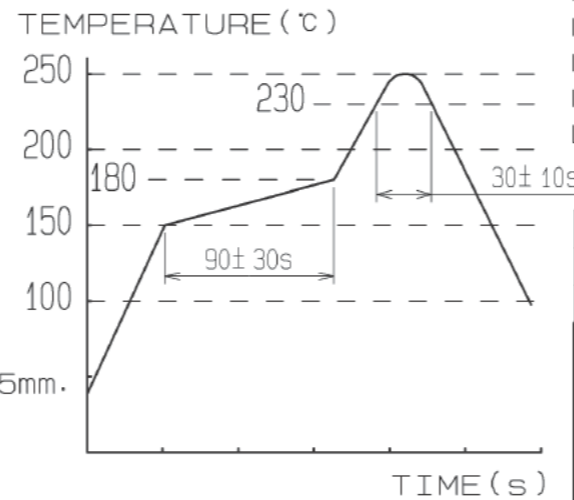
NOTE 1. RECOMMENDED TEMPERATURE PROFILE FOR REFLOW (REFER TO RIGHT FIG.)
REFLOW HEATING METHODS: FAR-INFLARED, IN THE AIR OR NITROGEN

REFLOW No. : MAX 2TIMES
PEAK TEMPERATURE : 250°C
ABOVE 230°C : 20~40s
PREHEAT : 150~180°C
60~120s

2. SOLDERING TEMPERATURE : 280~300°C, MAX 2s
3. COPLANARITY OF LEADS SHALL BE UNDER 0.1mm.

4. MARKING OF LOT No. :
(EX) 2008. 2ND. JULY → 08G02...5DIGITS

5. RECOMMENDED THICKNESS FOR PC BOARD IS 1.6mm.
6. RECOMMENDED THICKNESS FOR SOLDER PASTE IS 0.15mm.



2	BRASS	TIN-COPPER ALLOY PLATING					
1	PPS	BLACK	3	BRASS	TIN-COPPER ALLOY PLATING		
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS		
UNITS	mm	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
		2 : 1	3	DIS-T-002745	HH. TSUKUMO	NA. HARUBAYASHI	12. 05. 30
APPROVED : AR. SHIRAI				10. 10. 19	DRAWING NO. EDC3-167409-01		
CHECKED : NH. NAKATA				10. 10. 18	PART NO. GT8E-4P-2H		
DESIGNED : NA. HARUBAYASHI				10. 10. 18	CODE NO. CL758-0079-5-00		
DRAWN : Chinoik. Ng				10. 10. 18			

DRAWING FOR REFERENCE: This is subject to change without notice
05/31/2013